



(2,16 mm) .085"

DPAM, DPAF SERIES

# HIGH DENSITY DIFFERENTIAL PAIR ARRAY

DPAM Mates with:  
DPAF

DPAF Mates with:  
DPAM

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?DPAM](http://www.samtec.com?DPAM) or [www.samtec.com?DPAF](http://www.samtec.com?DPAF)

**Insulator Material:**  
Black LCP

**Contact Material:**  
Copper Alloy

**Plating:**

Au over 50µ" (1,27 µm) Ni

**Current Rating (2x3):**  
2.9 A per pin

**Operating Temp Range:**  
-55°C to +125°C

**Contact Resistance:**  
10.4mΩ

**Working Voltage:**  
300 VAC

**Mated Cycles:** 100 Cycles

**RoHS Compliant:** Yes

**Lead-Free Solderable:** Yes

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



FILE NO. E111594

**Protocols Supported**

- Fibre Channel
- Rapid I/O
- PCI Express®
- SATA
- InfiniBand™
- XAUI
- MGT (Rocket I/O)

Download app notes at [www.samtec.com/appnote](http://www.samtec.com/appnote)  
Contact SIG @ samtec.com for questions on protocols

**ALSO AVAILABLE (MOQ Required)**

- Tin-Lead Solder Charge
- Other platings
- Contact Samtec.

**Note:** Patented

**Note:** Some sizes, styles and options are non-standard, non-returnable.

**DPAM**

**PAIRS PER ROW**

**07.0**

**PLATING OPTION**

**NO. OF ROWS**

**SOLDER TYPE**

**A**

**OPTION**

**-04, -06**  
**-08, -15, -23**

**-S**  
=30µ" (0,76 µm)  
Gold on contact area,  
Tin on solder tail

**-8**  
=Eight  
Pair  
Rows

**-3**  
=Three  
Pair  
Rows

**-2**  
= Lead-Free  
Tin Alloy  
96.5% Sn/  
3% Ag/.5% Cu  
Solder Crimp

**-K**  
=(20,00 mm) 0.80"  
DIA Polyimide  
film Pick &  
Place Pad

**-TR**  
=Tape & Reel

**-GP**  
=Guide Post  
(-23 only)

NO OF ROWS	A
-8	(24,59) .968
-3	(11,89) .468

DPAM/DPAF 10 mm Stack Height	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	8 GHz / 16 Gbps
Differential Pair Signaling	7 GHz / 14 Gbps

\*Performance data includes effects of a non-optimized PCB. Complete test data available at [www.samtec.com?DPAM](http://www.samtec.com?DPAM), [www.samtec.com?DPAF](http://www.samtec.com?DPAF) or contact sig@samtec.com

**DPAF**

**PAIRS PER ROW**

**03.0**

**PLATING OPTION**

**NO. OF ROWS**

**SOLDER TYPE**

**A**

**OPTION**

**-04, -06, -08,**  
**-15, -23**

**-S**  
=30µ" (0,76 µm)  
Gold on contact area,  
Tin on solder tail

**-8**  
=Eight  
Pair  
Rows

**-3**  
=Three  
Pair  
Rows

**-2**  
= Lead-Free Tin Alloy  
96.5% Sn/ 3%Ag/  
.5% Cu  
Solder Crimp

**-K**  
=(20,00 mm) 0.80"  
DIA Polyimide  
film  
Pick &  
Place Pad

**-TR**  
=Tape & Reel

NO OF ROWS	A
-8	(23,32) .918
-3	(10,62) .418

SIZE	USABLE PAIRS PER ARRAY*
-04 x -3	6 Pairs
-06 x -3	12 Pairs
-04 x -8	16 Pairs
-06 x -8	32 Pairs
-08 x -8	48 Pairs
-15 x -8	104 Pairs
-23 x -8	168 Pairs
-08 x -3	18 Pairs
-15 x -3	39 Pairs
-23 x -3	63 Pairs

DPAM LEAD STYLE	DPAF MATED HEIGHT*
-07.0	10 mm

\*Processing conditions will affect mated height.

\*Assumes first and last pair in each row are grounded

Due to technical progress, all designs, specifications and components are subject to change without notice.

[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)